

ABSTRACT

5 A liquid epoxy resin composition comprising a liquid
epoxy resin, a curing agent, and an inorganic filler is
useful for semiconductor encapsulation when the curing agent
contains 5-100% by weight of a specific aromatic amine
compound of at least 99% pure, the epoxy resin and the curing
agent are present in a molar ratio from 0.7 to 0.9, and the
10 composition has a toughness K_{Ic} of at least 3.5. The
composition is adherent to the surface of silicon chips, does
not deteriorate under hot humid conditions, and is fully
resistant to thermal shocks.